

## Overview

The purpose of this notification is to announce the change of die attach film on wire bond packages for “XC” commercial (C), industrial (I) grade Spartan®-3AN products.

## Description

Xilinx material supplier Nitto will discontinue supply of specific die attach film in March 2017 due to its raw material’s supplier ending business. Xilinx has successfully qualified Hitachi’s new die attach film in mass production for past 3 years without any quality or reliability issue. This change is aligning the die attach film to industry best practice and enables supply continuity for commercial and industrial “XC” Spartan-3AN products in wire bond packages. This change will not affect fit, form, function, reliability or MSL rating of the packages.

## FAQs

### Q: What is the change?

Xilinx will change die attach film material for the commercial and industrial “XC” Spartan-3AN products in wire bond packages from Nitto to Hitachi die attach material due to raw material discontinuity from the supplier.

### Q: Why is Xilinx making this change?

Xilinx material supplier Nitto will discontinue supply of specific die attach film in March 2017 due to its raw materials supplier ending business. Xilinx has successfully qualified new die attach film in mass production for past 3 years without quality or reliability issue. This change is aligning the die attach film to industry best practice to allow supply continuity.

### Q: Which products are affected?

This change affects all speed, package, and temperature grade variations of “XC” commercial (C) and industrial (I) grade products included in the [Table 1](#)

**Table 1: Spartan-3AN FPGAs XC Devices Packages Affected**

Device-Package	Device-Package	Device-Package
XC3S400AN-FT(G)256	XC3S1400AN-FG(G)676	XC3S700AN-FG(G)484
XC3S200AN-FT(G)256	XC3S400AN-FG(G)400	XC3S50AN-TQ(G)144

### Q: When will this change take effect without sample?

Xilinx will begin cross shipping products with current and new die attach film upon PCN release.

### Q: Does Xilinx plan to change MDDS?

Xilinx will publish MDDS revision on Xilinx website for new die attach material upon PCN release.

**Q: Does Xilinx plan to change ICP data?**

Xilinx uses same bill of material as Spartan-3AN with new die attach film. These packages do not contain published REACH SvHC materials (Refer to ICP reports). Please submit a Service Request via the [Service Portal](#) for ICP reports after PCN release.

**Q: Does this matter to customers? What do customers have to do in response to this announcement?**

Customers should not be affected by this change, but will benefit from supply continuity.

**Q: Are design changes required? Will ordering part numbers change?**

Devices will remain in the same packages, with the same functionality, performance and appearance. There should be no change to the customer ordering part numbers.

**Q: How do I find out more?**

For additional information or questions, please contact [Xilinx Technical Support](#).

**Customer Operations:** Contact your local customer operations representative  
**Technical & Quality:** Submit Service Request via the [Service Portal](#)  
**Procurement related questions:** Contact your local customer operations representative

## Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
03/06/2017	1.0	Initial release.

## Notice of Disclaimer

The information disclosed to you hereunder (the "Materials") is provided solely for the selection and use of Xilinx products. To the maximum extent permitted by applicable law: (1) Materials are made available "AS IS" and with all faults, Xilinx hereby DISCLAIMS ALL WARRANTIES AND CONDITIONS, EXPRESS, IMPLIED, OR STATUTORY, INCLUDING BUT NOT LIMITED TO WARRANTIES OF MERCHANTABILITY, NON-INFRINGEMENT, OR FITNESS FOR ANY PARTICULAR PURPOSE; and (2) Xilinx shall not be liable (whether in contract or tort, including negligence, or under any other theory of liability) for any loss or damage of any kind or nature related to, arising under, or in connection with, the Materials (including your use of the Materials), including for any direct, indirect, special, incidental, or consequential loss or damage (including loss of data, profits, goodwill, or any type of loss or damage suffered as a result of any action brought by a third party) even if such damage or loss was reasonably foreseeable or Xilinx had been advised of the possibility of the same. Xilinx assumes no obligation to correct any errors contained in the Materials or to notify you of updates to the Materials or to product specifications. You may not reproduce, modify, distribute, or publicly display the Materials without prior written consent. Certain products are subject to the terms and conditions of Xilinx's limited warranty, please refer to Xilinx's Terms of Sale which can be viewed at <http://www.xilinx.com/legal.htm#tos>; IP cores may be subject to warranty and support terms contained in a license issued to you by Xilinx. Xilinx products are not designed or intended to be fail-safe or for use in any application requiring fail-safe performance; you assume sole risk and liability for use of Xilinx products in such critical applications, please refer to Xilinx's Terms of Sale which can be viewed at <http://www.xilinx.com/legal.htm#tos>.